

MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED


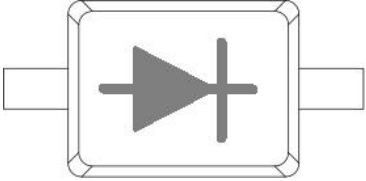

1SS389

Product specification

FEATURES

- High Speed
- High Reliability
- Small Package
- Low Forward Voltage

Reference News

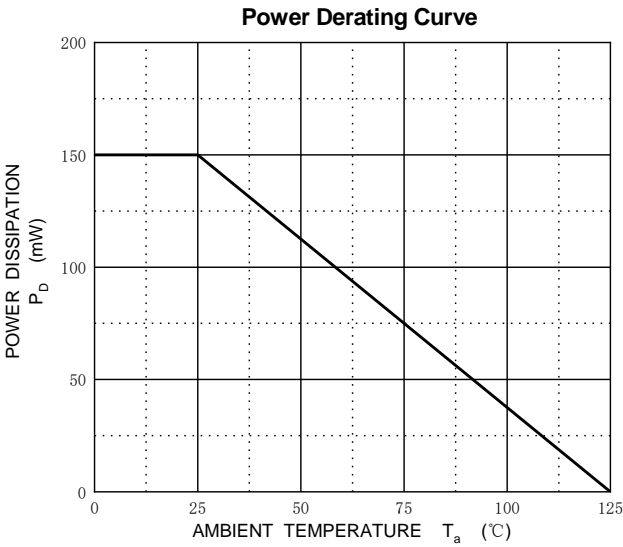
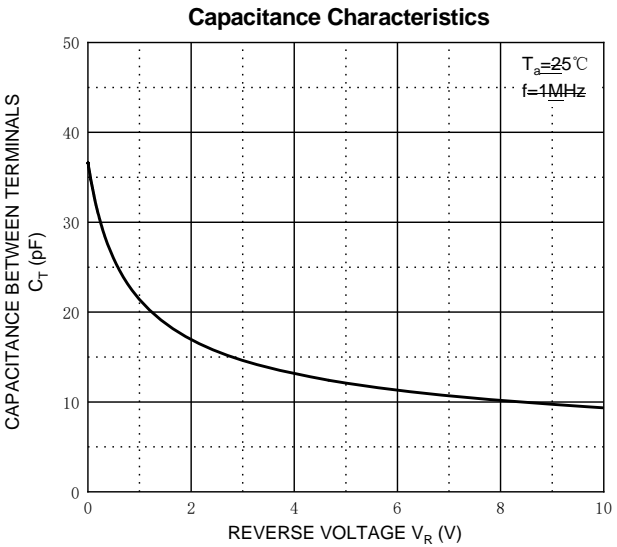
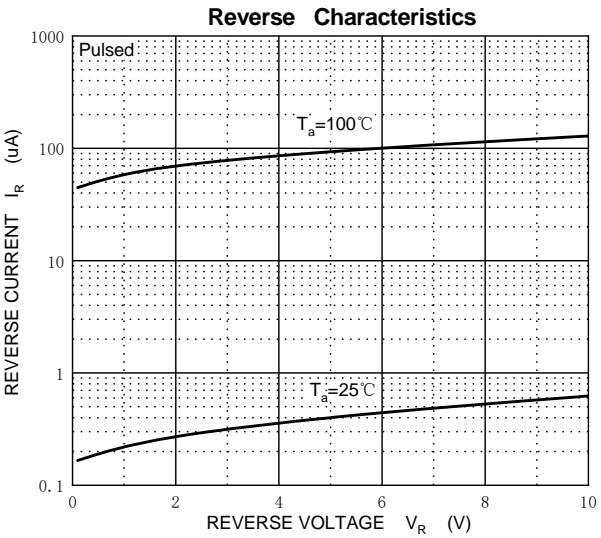
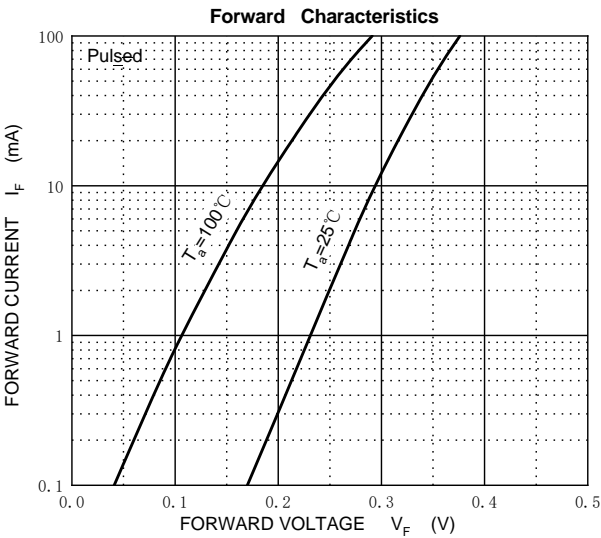
PACKAGE OUTLINE	PIN CONFIGURATION	Marking
 SOD-523		

MAXIMUM RATINGS (Ta=25°C unless otherwise noted)

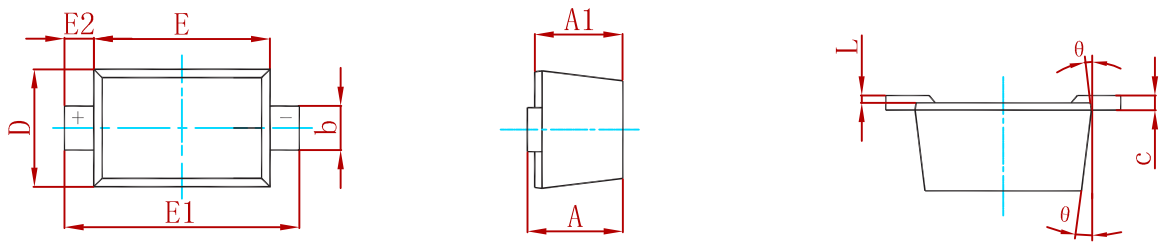
Symbol	Parameter	Value	Unit
V_R	DC Blocking Voltage	10	V
I_o	Continuous Forward Current	100	mA
I_{FM}	Peak Forward Current	200	mA
I_{FSM}	Non-repetitive Peak Forward Surge Current @t=8.3ms	1	A
P_D	Power Dissipation	150	mW
$R_{\theta JA}$	Thermal Resistance From Junction To Ambient	667	°C/W
T_j	Operating Junction Temperature Range	-40~+125	°C
T_{stg}	Storage Temperature Range	-55~+150	°C

ELECTRICAL CHARACTERISTICS(Ta=25°C unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Reverse voltage	$V_{(BR)}$	$I_R=100\mu A$	10			V
Reverse current	I_R	$V_R=10V$			20	μA
Forward voltage	V_F	$I_F=1mA$		0.18		V
		$I_F=5mA$			0.3	
		$I_F=100mA$			0.5	
Total capacitance	C_{tot}	$V_R=0V, f=1MHz$			40	pF

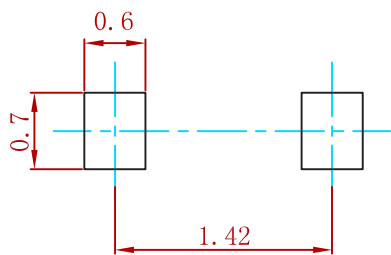


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.510	0.770	0.020	0.031
A1	0.500	0.700	0.020	0.028
b	0.250	0.350	0.010	0.014
c	0.080	0.150	0.003	0.006
D	0.750	0.850	0.030	0.033
E	1.100	1.300	0.043	0.051
E1	1.500	1.700	0.059	0.067
E2	0.200 REF		0.008 REF	
L	0.010	0.070	0.001	0.003
θ	7° REF		7° REF	

Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:±0.05mm.
3.The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
1SS389	SOD-523	3000

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